

4.40-5.00GHz 8-Watt Internally Matched Power FET

FEATURES

- 4.40–5.00GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.5 dBm Output Power at 1dB Compression
- 10.5 dB Power Gain at 1dB Compression
- 35% Power Added Efficiency
- -46 dBc IM3 at PO = 28.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS (T_a = 25°C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 4.4-5.0GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$	38.5	39.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 4.4-5.0GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$	9.5	10.5		dB
ΔG	Gain Flatness $f = 4.4-5.0GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 2200mA		35		%
Id _{1dB}	Drain Current at 1dB Compression f = 4.4-5.0GHz		2300	2600	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10 \text{ MHz } 2\text{-Tone Test}$; Pout = 28.5 dBm S.C.L ² $V_{DS} = 10 \text{ V}$, $I_{DSQ} \approx 65\% \text{ IDSS}$ f =5.0GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		4000	5000	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 40 \text{ mA}$		-2.5	-4.0	V
R_{TH}	Thermal Resistance ³		3.5	4.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

- 2. S.C.L. = Single Carrier Level.
- 3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS PARAMETERS		ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
Igf Forward Gate Current		96mA	28.8mA	
Igr Reverse Gate Current		-19.2mA	-4.8mA	
Pin	Pin Input Power		@ 3dB Compression	
Tch Channel Temperature		175C	175C	
Tstg Storage Temperature		-65C to +175C	-65C to +175C	
Pt Total Power Dissipation		37.5W	37.5W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.

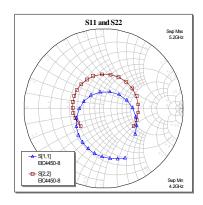


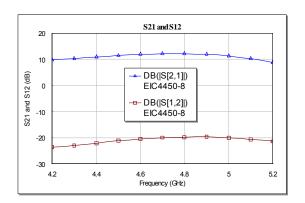


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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} ≈ 2200mA





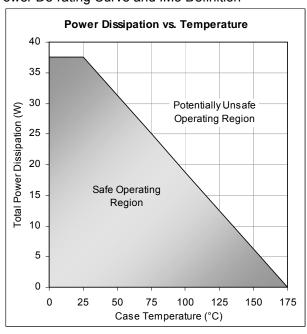
FREQ	S	S11 S21 S12		12	S22			
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
4.0	0.7503	-37.83	2.703	97.27	0.0555	43.87	0.3563	-105.99
4.2	0.6786	-66.68	3.0738	66.41	0.0662	11.77	0.3648	-142.14
4.4	0.5779	-101.09	3.5153	32.39	0.0788	-21.55	0.3889	178.7
4.6	0.4132	-146.28	3.9355	-6.5	0.0954	-60.58	0.4149	132.78
4.8	0.2292	134.17	4.0571	-50.3	0.1033	-105.97	0.4326	78.67
5.0	0.308	19.37	3.6482	-96.93	0.0989	-153.5	0.4399	20.6
5.2	0.5127	-39.49	2.78	-140.48	0.0854	160.93	0.4385	-30.72
5.4	0.6658	-77.6	1.9617	-177.01	0.0678	119.63	0.4493	-70.46
5.6	0.7585	-107.39	1.3733	153.13	0.0532	81.38	0.4784	-98.19
5.8	0.8058	-133.11	1.0074	126.36	0.0414	46.84	0.5605	-121.4
6.0	0.8356	-155.36	0.7453	101.98	0.0333	18.09	0.6098	-141.51

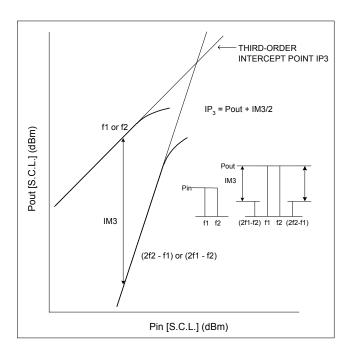




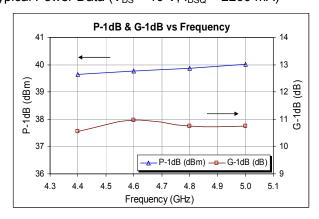
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Power De-rating Curve and IM3 Definition

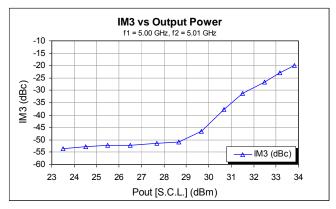




Typical Power Data (V_{DS} = 10 V, I_{DSQ} = 2200 mA)



Typical IM3 Data ($V_{DS} = 10 \text{ V}$, $I_{DSQ} \approx 65\% \text{ IDSS}$)



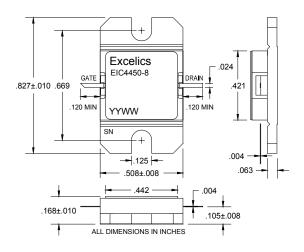


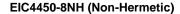
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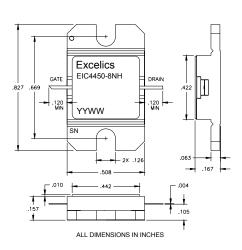
PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

EIC4450-8 (Hermetic)









Caution! ESD sensitive device.



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ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²
EIC4450-8	Hermetic	Industrial	4.40-5.00GHz	38.5	-43
EIC4450-8NH	Non-Hermetic	Industrial	4.40-5.00GHz	38.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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